

Asia Tech Tour: Taiwan, Korea & Japan Mar 2nd – 13th

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We have a strong schedule for our Asia Tour, Mar 2nd – 13, across Taiwan, Korea and Japan. We'll focus on AI including server scaling, component and material constraints, and the memory cycle. Reach out if you are interested in joining.

Taiwan March 2nd – 5th

Monday, March 2, 2026	Company	Product	Key Topic or Read Through
9:00 AM	Powertech (6239 TT)	Memory Packaging & Test	MU HBM Overflow
11:00 AM	Realtek (2379 TT)	WiFi Ethernet IC's	Legacy tech recovery
1:00 PM	Chunghwa Precision (6510 TT)	ATE: Probe Cards & Interface Boards	TSM NVDA AAPL
4:00 PM	Hon Hai (2317 TT)	EMS: SP Server EV	NVL 72 Rack Install Rate
5:30 PM	Gigabyte (2376 TT)	AI Server Tier 2 CSP & Enterprise	GB200 to GB300 Transition
Tuesday, March 3, 2026	Company	Product	Key Topic or Read Through
9:00 AM	Kinsus (3189 TT)	Boards: PCB IC Substrates	AAPL & China SP exposure: ABF for AMD, AVGO, NVDA
10:30 AM	Jentech (3653 TT)	Heat Sink for GPU CPU	NVDA Heat Sink: Ruben Spec, Asp
12:00 PM	Accton (2345 TT)	800G Whitebox Switch	AMZN 800G switch trends
2:00 PM	MediaTek (2454 TT)	SP AP WiFi ASIC's	GOOG TPUE Timing
3:30 PM	Global Unichip (3443 TT)	ASIC Design	META & MSFT Ramps
5:00 PM	Scientech (3583 TT)	Wet Bench PR Strip	TSM CoWoS & AP
Wednesday, March 4, 2026	Company	Product	Key Topic or Read Through
9:00 AM	Zhen Ding (4958 TT)	Boards: Flex PCB, HDI, IC Substrate	iPhone 17, IC Substrate for AMD, NVDA, China
11:00 AM	WinWay (6515 TT)	IC Test Socket	NVDA, AMD & ASIC = 70% of sales
1:30 PM	Gudeng (3680 TT)	FOUP, EUV PODS, AP Carriers	TSM EUV, Advanced Packaging
3:30 PM	Kinik (1560 TT)	CMP Diamond Grinding Tools	TSM 2nm ramp; Polishing and CMP Demand
6:00 PM	Chipbond (6147 TT)	Gold Bumping	SIPH Packaging LPO MRVL
Thursday, March 5, 2026	Company	Product	Key Topic or Read Through
7:00 AM	Tokyo Seimitsu (7729 JP)	Wafer Dicing & Grinding	Probe Card for HPC
9:00 AM	Eugene (084370 KS)	Deposition & Etch	Samsung IC, Hynix M15x
10:30 AM	Unimicron (3037 TT)	IC Sub: ABF BT, PCB: HDI Flex (tiny)	NVDA share vs. Ibiden
1:30 PM	First Hi-Tec (5439 TT)	Boards: 6-38 layers	PCBs for Server & Networking

Korea March 6th

Friday, March 6, 2026	Company	Product	Key Topic or Read Through
9:00 AM	SK Hynix (000660 KS)	DRAM, HBM, NAND	HBM Demand '26 Pricing & Volume
1:30 PM	EO Technics (039030 KS)	Laser Marking, Annealing	TSM: Sole Vendor for 3N Laser Grooving
4:00 PM	SFA Eng (056190 KS)	OHT for Samsung & Hynix	Samsung HBM4 Logistics

Japan March 9th – 13th

Monday, March 9, 2026	Company	Product	Key Topic or Read Through
10:00 AM	Lintec (7966 JP)	Backgrinding Tapes	Samsung HBM 4 Supplier
1:00 PM	Anritsu (6754 JP)	Network Testing Equipment	Telecom IoT Electronics
2:30 PM	Sekisui (4204 JP)	Build up films for CPU, GPU	AVGO using as alternative to ABF
4:00 PM	Nikon (7731 JP)	Lithography	Maskless Litho for Advanced Packaging

Tuesday, March 10, 2026	Company	Product	Key Topic or Read Through
9:00 AM	ISC (095340 KS)	IC Test Socket	NVDA, AMD, INTC, ASICs
11:00 AM	MINEBEA MITSUMI (6479 JP)	Ball Bearings Misc Components	Data Center Cooling
1:00 PM	TOPPAN (7911 JP)	Photomasks, IC Substrate	IC Substrate for BRCM Switch
3:30 PM	TOK (4186 JP)	Photoresist: Global #1	Advanced Packaging 50% Growth

Wednesday, March 11, 2026	Company	Product	Key Topic or Read Through
10:00 AM	Micronics (6871 JP)	Wafer Probe	45% HBM
1:00 PM	Mitsui Chem (4183 JP)	Films Polymers for Semi & Display	EUV DUV Pellicle Mask
3:00 PM	Hioki (6866 JP)	Electrical Test for ABF	Electrical Test for ABF
4:30 PM	Rohm (6963 JP)	Analog IC's	Japan Auto Recovery

Thursday, March 12, 2026	Company	Product	Key Topic or Read Through
11:00 AM	Hoya (7741 JP)	EUV Masks HDD Substrate	STX HDD Substrate
12:00 PM	Alchip (3661 TT)	ASIC Design	Alchip or MRVL, Whose Got AMZN?
1:00 PM	SUMCO (3436 JP)	Silicon wafers	Raw wafer demand
3:00 PM	TDK Corp (6762 JP)	Passives	Near Line Storage Trends
4:30 PM	Ushio (6925 JP)	Lightsources	Digital Litho for IC Substrate

Friday, March 13, 2026	Company	Product	Key Topic or Read Through
1:00 PM	Ulvac (6728 JP)	Vacuum Equip	Samsung IC Ramp
2:00 PM	Kioxia (285A JP)	NAND	Enterprise Server & PC Demand
4:30 PM	Disco (6146 JP)	Wafer Dicing & Grinding	Leading Edge & Advanced Packaging Drives Growth

Disclosures

12 month historical recommendation changes are available on request

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